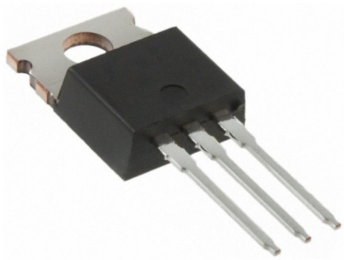


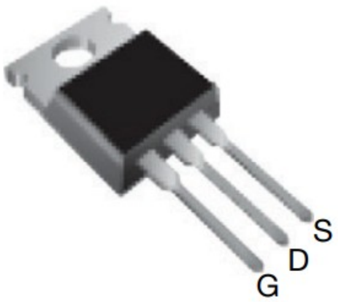
VISHAY IRF720 Power MOSFET Owner's Manual

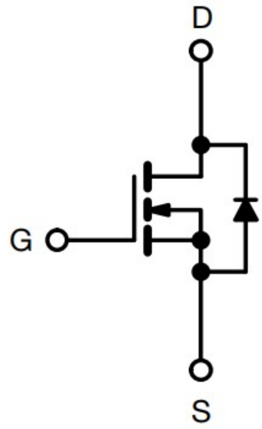
Vishay Intertechnology: Passives & Discrete Semiconductors
www.vishay.com
IRF720
Vishay Siliconix
Power MOSFET

Contents

IRF720 Power MOSFET

TO-220AB





N-Channel MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	400 V	
RDS(on) (Ω)	V_{GS} = 10 V	1.8
Q_g max. (nC)	20	
Q_{gs} (nC)	3.3	
Q_{gd} (nC)	11	
Configuration	Single	

FEATURES

Available

RoHS*

Available

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF720PbF
Lead (Pb)-free and halogen-free	IRF720PbF-BE3

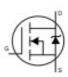
ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER		**SYMBOL**	**LIMIT**	**UNIT**
Drain-source voltage		VDS	400	V
Gate-source voltage		VGS	± 20	V
Continuous drain current	V_{GS} at 10 V, T_C = 25 °C	I_D	3.3	A
	V_{GS} at 10 V, T_C = 100 °C		2.1	A
Pulsed drain current a		IDM	13	A
Linear derating factor			0.40	W/°C
Single pulse avalanche energy b		EAS	190	mJ
Repetitive avalanche current a		IAR	3.3	A
Repetitive avalanche energy a		EAR	5.0	mJ
Maximum power dissipation	T_C = 25 °C	P_D	50	W
Peak diode recovery dV/dt c		dV/dt	4.0	V/ns
Operating junction and storage temperature range		TJ, Tstg	-55 to +150	°C
Soldering recommendations (peak temperature) d	For 10 s		300	°C
Mounting torque	6-32 or M3 screw		10	lbf · in
			1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
b. Vpp = 50 V, starting Ty = 25 °C, L = 30 mH, Rg = 25 Ω, Ias = 3.3 A (See fig. 12)
c. Isp ≤3.3 A, dI/dt ≤ 65 A/us, Vpp ≤ Vps, Ty ≤ 150 °C
d. 1.6 mm from case

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum junction-to-ambient	RthJA	–	62	°C/W
Case-to-sink, flat, greased surfac e	RthCS	0.50	–	
Maximum junction-to-case (drain)	RthJC	–	2.5	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 μA	400	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA	-	0.51	-	V/°C
Gate-source threshold voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	2.0	-	4.0	V
Gate-source leakage	I_{GSS}	V_{GS} = ± 20	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	V_{DS} = 400 V, V_{GS} = 0 V	-	-	25	μA
		V_{DS} = 320 V, V_{GS} = 0 V, T_J = 125 °C	-	-	250	
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS} = 10 V; I_D = 2.0 A [b]	-	-	1.8	Ω
Forward transconductance	g_{fs}	V_{DS} = 50 V, I_D = 2.0 A [b]	1.7	-	-	S
Dynamic						
Input capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5	-	410	-	pF
Output capacitance	C_{oss}		-	120	-	
Reverse transfer capacitance	C_{rss}		-	47	-	
Total gate charge	Q_g	V_{GS} = 10 V; I_D = 3.3 A, V_{DS} = 320 V, see fig. 6 and 13 [b]	-	-	20	nC
Gate-source charge	Q_{gs}		-	-	3.3	
Gate-drain charge	Q_{gd}		-	-	11	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 200 V, I_D = 3.3 A, R_g = 18 Ω, R_D = 56 Ω, see fig. 10 [b]	-	10	-	ns
Rise time	t_r		-	14	-	
Turn-off delay time	$t_{d(off)}$		-	30	-	
Fall time	t_f		-	13	-	
Gate input resistance	R_g	f = 1 MHz, open drain	1.2	-	7.3	Ω
Internal drain inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal source inductance	L_S		-	7.5	-	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	3.3	A
Pulsed diode forward current [a]	I_{SM}		-	-	13	
Body diode voltage	V_{SD}	T_J = 25 °C, I_S = 3.3 A, V_{GS} = 0 V [b]	-	-	1.6	V
Body diode reverse recovery time	t_{rr}	T_J = 25 °C, I_F = 3.3 A, dI/dt = 100 A/μs [b]	-	270	600	ns
Body diode reverse recovery charge	Q_{rr}		-	1.4	3.0	μC
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

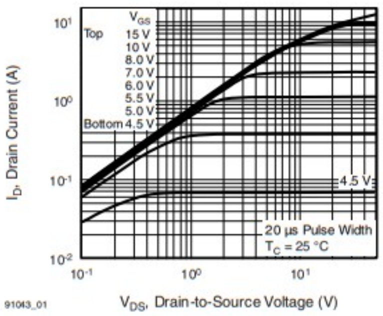


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

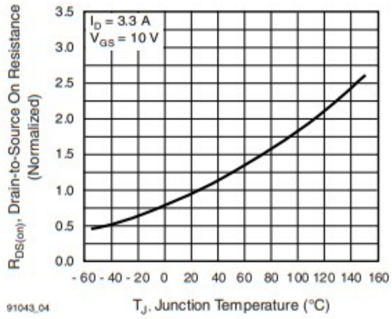


Fig. 4 - Normalized On-Resistance vs. Temperature

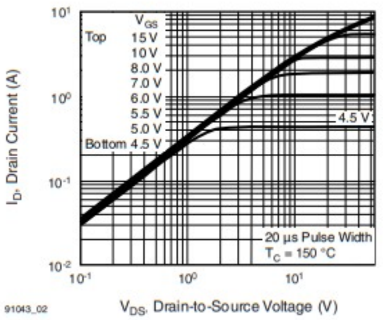


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

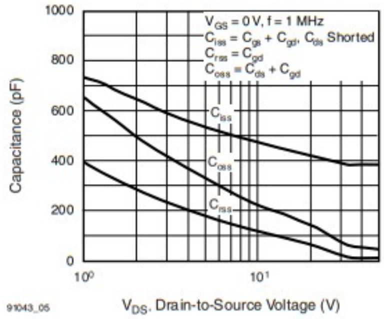


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

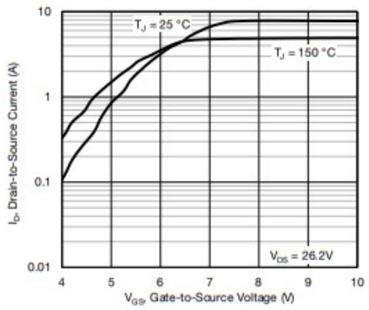


Fig. 3 - Typical Transfer Characteristics

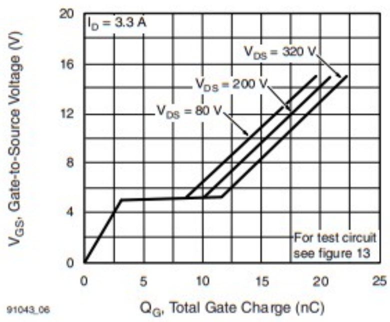


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

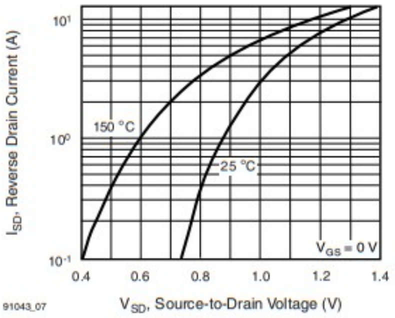


Fig. 7 - Typical Source-Drain Diode Forward Voltage

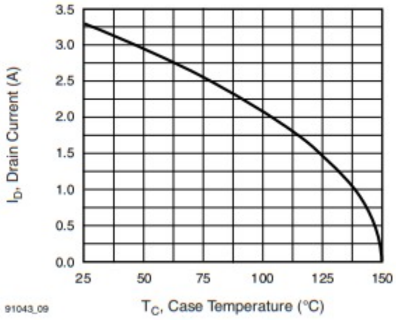


Fig. 9 - Maximum Drain Current vs. Case Temperature

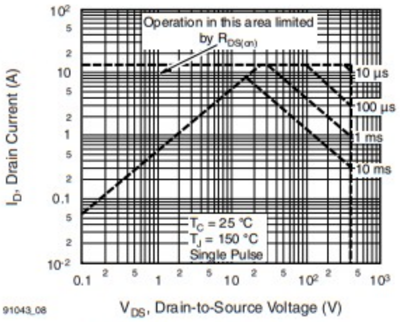


Fig. 8 - Maximum Safe Operating Area

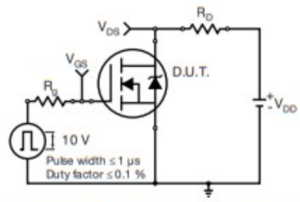


Fig. 10a - Switching Time Test Circuit

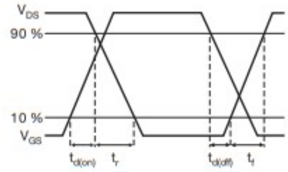


Fig. 10b - Switching Time Waveforms

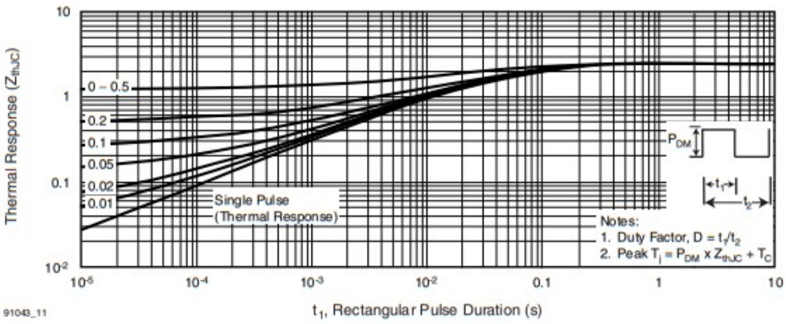


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

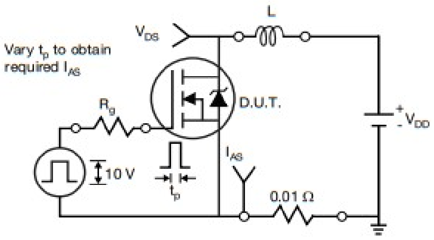


Fig. 12a - Unclamped Inductive Test Circuit

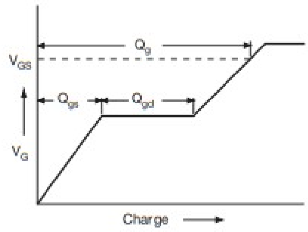


Fig. 13a - Basic Gate Charge Waveform

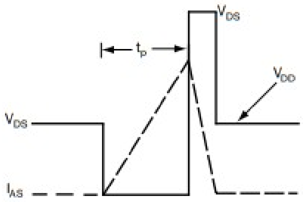


Fig. 12b - Unclamped Inductive Waveforms

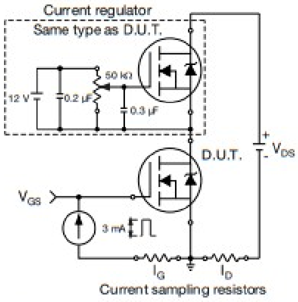


Fig. 13b - Gate Charge Test Circuit

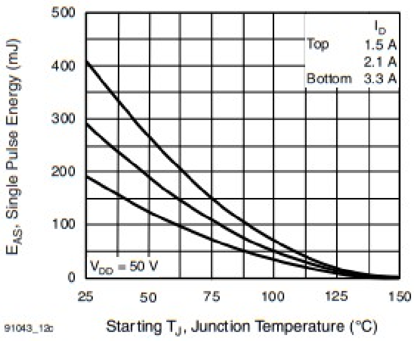


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

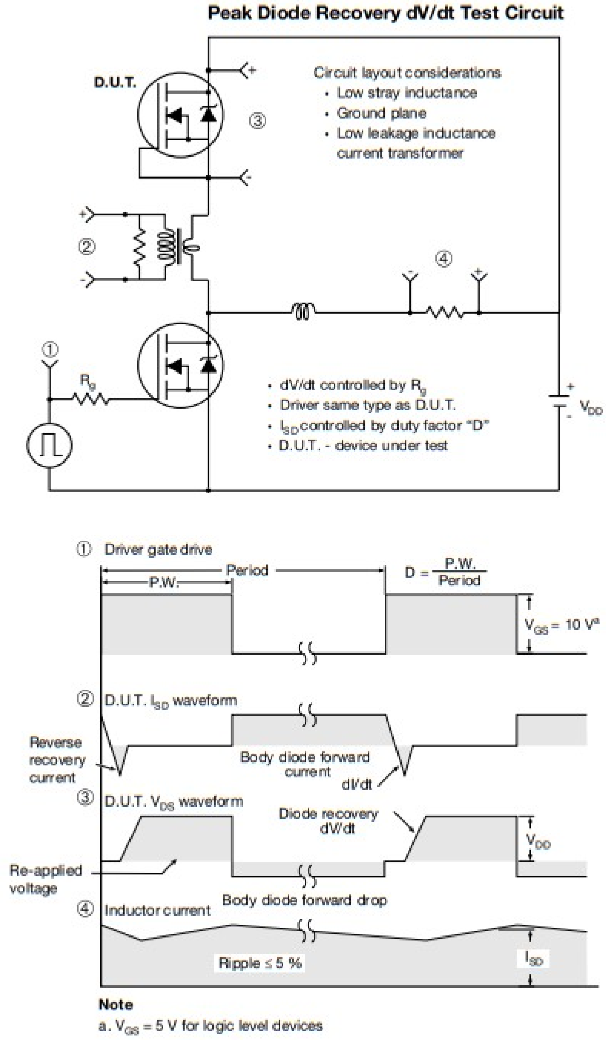


Fig. 14 - For N-Channel

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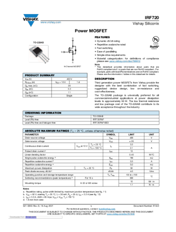	VISHAY IRF720 Power MOSFET [pdf] Owner's Manual IRF720 Power MOSFET, IRF720, Power MOSFET, MOSFET

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